



**Please note that Cypress is an Infineon Technologies Company.**

The document following this cover page is marked as “Cypress” document as this is the company that originally developed the product. Please note that Infineon will continue to offer the product to new and existing customers as part of the Infineon product portfolio.

**Continuity of document content**

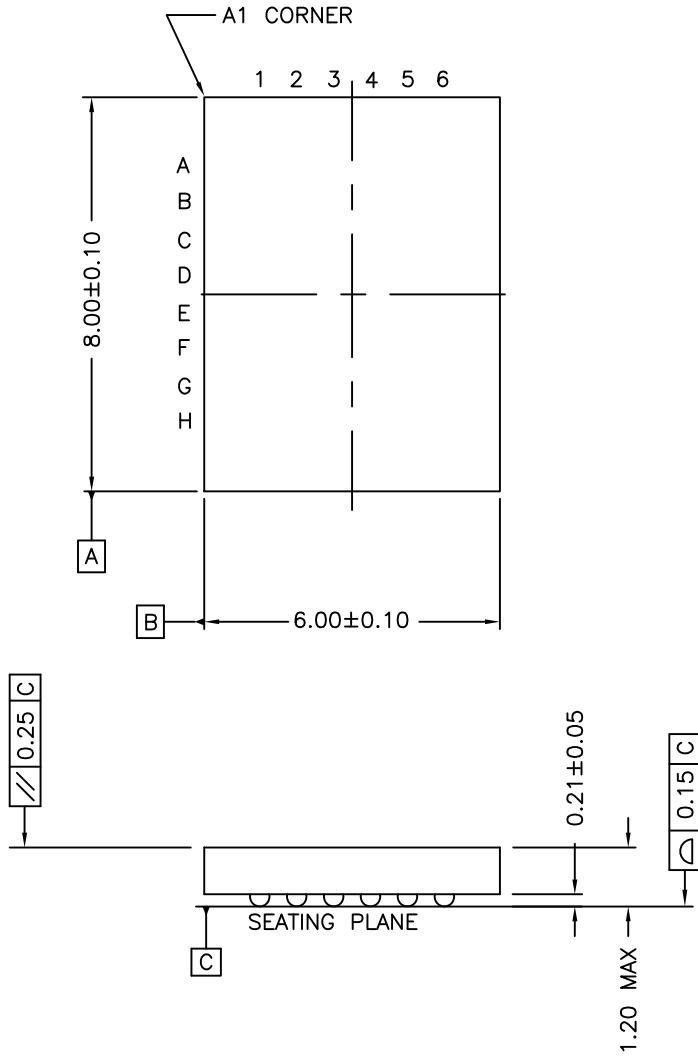
The fact that Infineon offers the following product as part of the Infineon product portfolio does not lead to any changes to this document. Future revisions will occur when appropriate, and any changes will be set out on the document history page.

**Continuity of ordering part numbers**

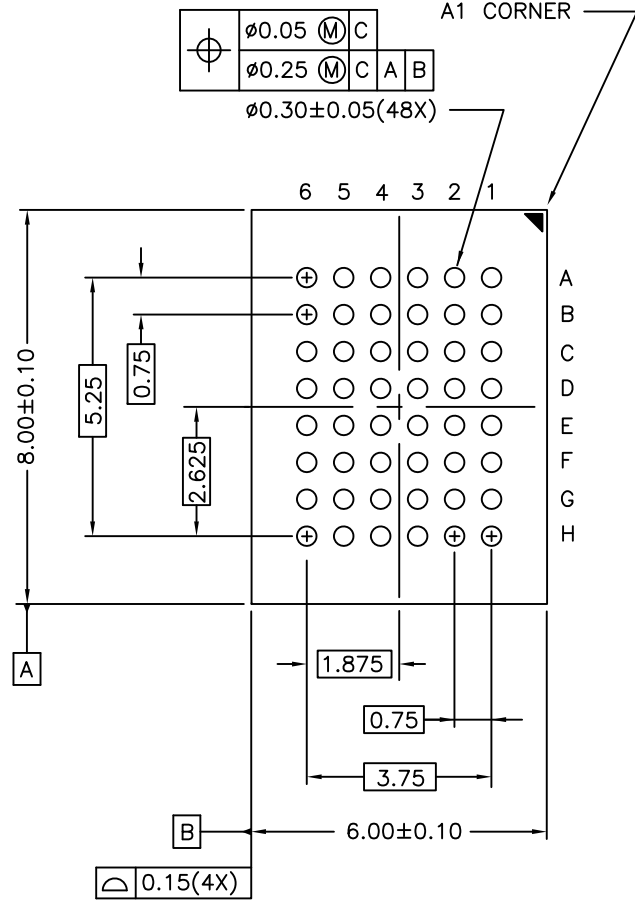
Infineon continues to support existing part numbers. Please continue to use the ordering part numbers listed in the datasheet for ordering.

REVISIONS						
PAGE	ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
1	-	**	128594	NEW RELEASE	07/18/03	N/A
1	-	*A	130995	UPDATE PKG. TO 6x8/ CHANGE TITLE	11/05/03	N/A
1	-	*B	2808704	Changed Template and Title from 48 FBGA (6x8x1.2MM) PACKAGE OUTL. to PACKAGE OUTLINE, 48L FBGA 6X8X1.2 MM BA48K.	11/18/09	QAD
1	-	*C	3375464	Update spec for sunset review, no changed	09/19/11	QAD
1	-	*D	4716659	Update spec for sunset review, no changed	04/08/15	QAD
1	-	*E	6301415	Remove mold cap thickness and substrate thickness	9/5/18	KOTA

TOP VIEW



BOTTOM VIEW



REFERENCE JEDEC MO-207

UNLESS OTHERWISE SPECIFIED ALL DIMENSIONS ARE IN MILLIMETERS STANDARD TOLERANCES ARE: DECIMALS .XX ± 0.05 .XXX ± .XXXX + ANGLES ± 1°	DESIGNED BY HTN	DATE 11/05/03	 CYPRESS Confidential
	DRAWN BY KOTA	DATE 9/5/18	
	CHECKED BY CMG	DATE 9/5/18	
	APPROVED BY CMG	DATE 9/5/18	
MATERIAL N/A	APPROVED BY	DATE	TITLE PACKAGE OUTLINE, 48L FBGA 6X8X1.2 MM BA48K
FINISH N/A	APPROVED BY	DATE	SIZE A
			PART NO. BA48K
			DWG NO 51-85193
			REV *E
			SCALED TO FIT N/A
			SHEET 1 OF 1

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